CLAIMS

1. An electric component comprising:

a base member formed of an insulative material and having a reception concavity into which a semiconductor device is mounted;

one or a plurality of electric conductive patterns formed along at least a bottom face and side faces of the reception concavity, and a top face of the base member on which an aperture of the reception concavity is formed among the base member, and electrically connected to the semiconductor device in the reception concavity;

an encapsulation resin filled up in the reception concavity; and

a stopper resin layer formed on the top face of the base member for covering at least boundaries of the electric conductive pattern and the base member in directions parallel to peripheries of the aperture of the reception concavity so as to prevent leakage or proceeding due to capillarity of the encapsulation resin.

2. The electronic component in accordance with claim 1, wherein

the stopper resin layer is formed to cover at least overall width of the electric conductive pattern in directions parallel to a circumference of the aperture of the reception concavity.

3. The electronic component in accordance with claim 1, wherein

the stopper resin layer is formed along entire circumference of the aperture of the reception concavity including on the electric

conductive pattern.

4. The electronic component in accordance with claim 1, wherein

a groove is formed on the top face of the base member along entire circumference of the aperture of the reception concavity;

a part of the electric conductive pattern is formed along side faces and a bottom face of the groove; and

the stopper resin layer is formed by filling a resin into the groove.

5. The electronic component in accordance with claim 1, wherein

a material having a viscosity higher than that of a material of the encapsulation resin is used as a material of the stopper resin layer.

6. A manufacturing method of electronic component, that a semiconductor device is mounted in a reception concavity of a base member and an encapsulation resin is filled into the reception concavity, comprising steps of applying a resin on a top face of the base member for covering at least boundaries of an electric conductive pattern and the base member in directions parallel to peripheries of an aperture of the reception concavity so as to form a stopper resin layer for preventing leakage or proceeding due to capillarity of the encapsulation resin, after mounting the semiconductor device in the reception concavity and before filling up an encapsulation resin into the reception concavity.

7. The manufacturing method of electronic component in

accordance with claim 6, wherein

the stopper resin layer is formed by applying a resin so as to cover at least entire width of the electric conductive pattern in a direction parallel to circumference of an aperture of the reception concavity.

8. The manufacturing method of electronic component in accordance with claim 6, wherein

the stopper resin layer is formed by applying a resin along entire circumference of an aperture of the reception concavity including on the electric conductive pattern.

9. The manufacturing method of electronic component in accordance with claim 6, wherein

the stopper resin layer is formed by filling a resin into a groove which is formed on a top face along entire circumference of an aperture of the reception concavity.